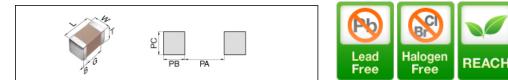
Multilayer Ceramic Chip Capacitors

C3225X7R2A105M200AA (TDK item description : C3225X7R2A105MT****)

| Applications | | Commercial Grade |
|--------------|--------------------|---|
| | Δ | Please refer to Part No. CGA6M2X7R2A105M200AA for automotive use. |
| Feature | Mid | Mid Voltage (100 to 630V) |
| Series | C3225 [EIA CC1210] | |



| Size | | | | |
|------------------------------|------------------|--|--|--|
| Length(L) | 3.20mm +/-0.40mm | | | |
| Width(W) | 2.50mm +/-0.30mm | | | |
| Thickness(T) | 2.00mm +/-0.20mm | | | |
| Terminal Width(B) | 0.20mm Min. | | | |
| Terminal Spacing(G) | | | | |
| Recommended Land Pattern(PA) | 2.00 to 2.40mm | | | |
| Recommended Land Pattern(PB) | 1.00 to 1.20mm | | | |
| Recommended Land Pattern(PC) | 1.90 to 2.50mm | | | |
| Recommended Slit Pattern(SD) | | | | |

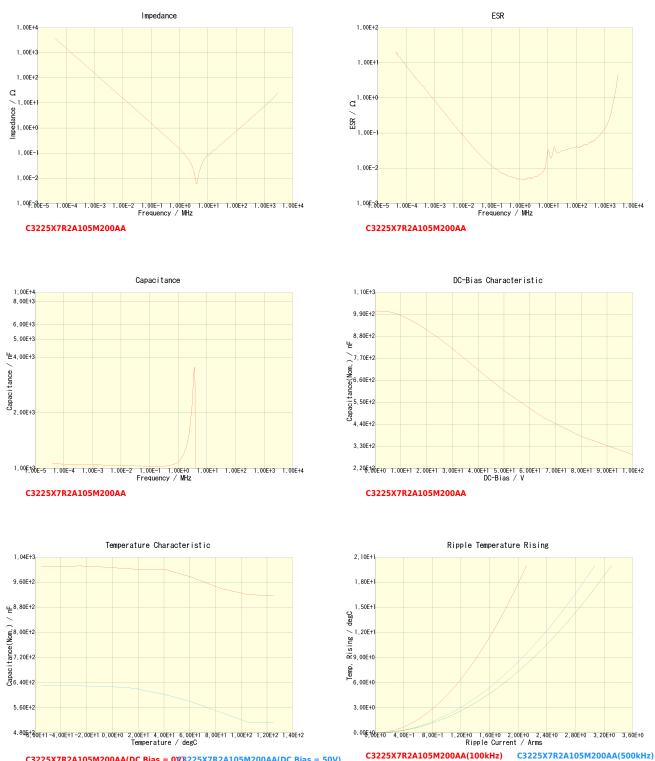
| Electrical Characteristics | | | | |
|----------------------------|-------------|--|--|--|
| Capacitance | 1uF +/-20% | | | |
| Rated Voltage | 100Vdc | | | |
| Temperature Characteristic | X7R(+/-15%) | | | |
| Dissipation Factor | 3% Max. | | | |
| Insulation Resistance | 500MΩ Min. | | | |

| Other | | |
|------------------|--------------------------------------|--|
| Soldering Method | Reflow | |
| AEC Q200 | No | |
| Packing | Blister (Plastic)Taping [180mm Reel] | |
| Package Quantity | 1000Pcs Min. | |

•This PDF document was created based on the data listed on the TDK Corporation website. •All specifications are subject to change without notice.

C3225X7R2A105M200AA

Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)



C3225X7R2A105M200AA(DC Bias = 012)225X7R2A105M200AA(DC Bias = 50V)

C3225X7R2A105M200AA(1MHz)

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